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**LC8808B-3535 LED**  
**SPECIFICIFATION**  
**INTEGRATED LIGHT SOURCE INTELLIGENT CONTROL SMD LED**

**Document No.: SPC/ LC8808B-3535 LED**

**Model No.: LC8808B-3535**

**Description: 3.5x3.7x0.95mm Intelligent control SMD LED**



**[www.szledcolor.com](http://www.szledcolor.com)**

## 1. General description

The LC8808B-3535 is a three-channel LED driver IC driven by a 12V power supply with high-precision constant-current output and integrated MCU digital connections. Circuits such as ports, data latches, and LED drivers. The peripheral gray MCU control realizes the individual gray scale and cascade control of the chip to realize outdoor large

The color dot matrix illumination control of the screen. The product has excellent performance and reliable quality.

## 2. Feature

High voltage CMOS process, 12V single point single control

Output constant current value absolute accuracy  $\pm 2\%$ , RGB relative accuracy  $\pm 1\%$

High efficiency, low power consumption, long transmission distance without discoloration

The default output constant current value is 9mA, suitable for built-in lamp beads

The default power-on does not light up.

Gray scale adjustment circuit (256 levels of grayscale adjustable)

Single-line serial cascading interface (DIN.DOUT)

Built-in high precision and high stability oscillator

Data shaping: automatically receive subsequent data shaping output after receiving the unit data

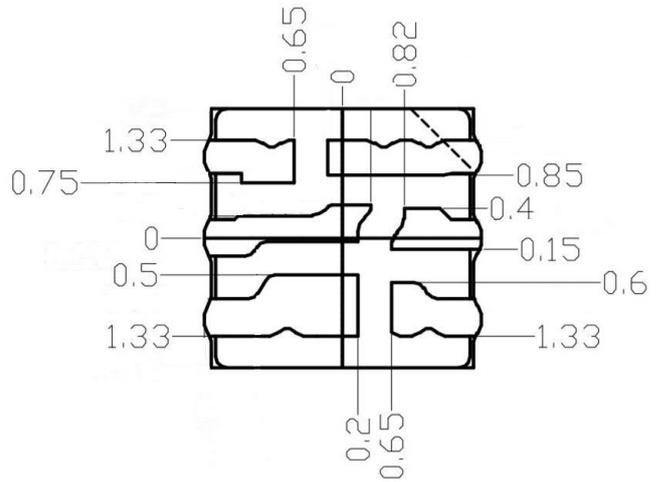
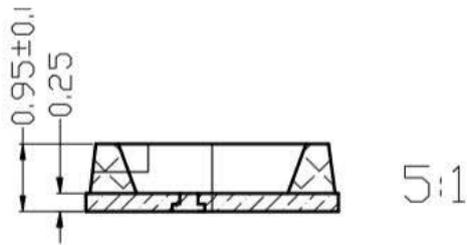
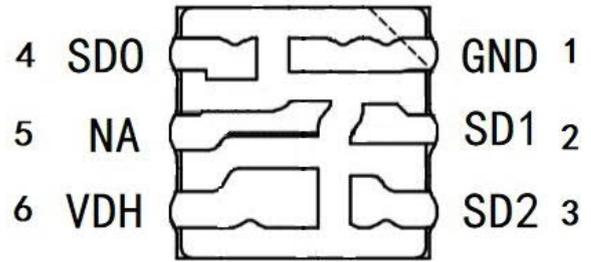
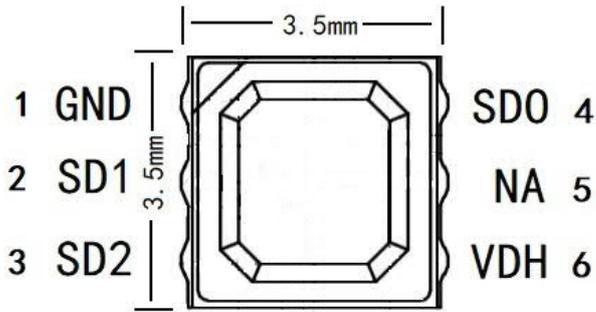
Data transmission rate 800 Kbps

## 3. Product Naming

LC8808B mean white surface ,9mA/channel ,White surface,the IC is integrated in 3535  
(standard version)

LC8808B-B mean black surface ,9mA/channel ,the IC is integrated in 3535

**4. Mechanical Dimensions:**



**Notes:**

1. All dimensions are in millimeters.
2. Tolerance is  $\pm 0.1$ mm unless otherwise noted

**5. Pin Configuration:**

| NO. | Symbol | Function description        |
|-----|--------|-----------------------------|
| 1   | GND    | Ground                      |
| 2   | SDI    | Series data input           |
| 3   | SD2    | Redundant Series data input |
| 4   | SDO    | Series data output          |
| 5   | NA     | Empty                       |
| 6   | VDH    | 12V Power supply            |

**6. Absolute Maximum Ratings (Ta=25°C,VSS=0V) :**

| Parameter            | Symbol           | Range        | Unit |
|----------------------|------------------|--------------|------|
| Power supply voltage | VDD              | -0.4V~+14    | V    |
| Logic input voltage  | V <sub>IN</sub>  | -0.5~VDD+0.5 | V    |
| R/G/B output current | I <sub>OUT</sub> | 9            | mA   |
| Working temperature  | T <sub>opt</sub> | -40~+85      | °C   |
| Storage temperature  | T <sub>stg</sub> | -50~+150     | °C   |
| ESD pressure         | V <sub>ESD</sub> | 2K           | V    |

**7. RGB LED photoelectric parameters**

| Color | LC8808B-3535 RGB LED Wavelength |              |           |
|-------|---------------------------------|--------------|-----------|
|       | MCD                             | Lumen        |           |
| Red   | 620-623nm                       | 800-900mcd   | 2.5-3lm   |
| Green | 517.5-520nm                     | 1600-1800mcd | 5.0-6.0lm |
| Blue  | 467.5-470nm                     | 500-600mcd   | 1.5-2lm   |

**8. The electrical parameters (unless otherwise specified, TA=-20 ~ +70 °C , VDD=4.5 ~ 5.5V,VSS=0V):**

| Parameter                                    | Symbol           | Min  | Typical | Max  | Unit | Test conditions |
|--|------------------|------|---------|------|------|-----------------|
| The chip supply Voltage                      | V <sub>IN</sub>  | 10.8 | 12      | 13.2 | V    | ---             |
| R/G/B output current                         | I <sub>OUT</sub> | 8.82 | 9       | 9.18 | mA   | ---             |
| The Signal Input flip threshold              | V <sub>IH</sub>  | 4    | ---     | ---  | V    | VDD=5.0V        |
|  | V <sub>IL</sub>  | ---  | ---     | 1    | V    |                 |
| Static power consumptionThe frequency of PWM | FPWM             | ---  | 8       | ---  | KHZ  | -----           |
|  | IDD              | ---  | 2       | ---  | mA   |                 |

**9 The dynamic parameters (Ta=25 °C):**

| Parameter                      | Symbol | Min | Typical | Max | Unit | Test conditions                |
|--------------------------------|--------|-----|---------|-----|------|--------------------------------|
| The speed of data transmission | FDIN   | --- | 800     | --- | KHZ  | The duty ratio of 67% (data 1) |
| DOUT transmission delay        | TPLH   | --- | ---     | 500 | ns   | DIN→DOUT                       |
|                                | TPHL   | --- | ---     | 500 | ns   |                                |
| OUT Rise/Drop Time             | Tr     | --- | 100     | --- | ns   | VDS=1.5<br>IOUT=13mA           |
|                                | Tr     | --- | 100     | --- | ns   |                                |

**10 function description**

The chip adopts single-line communication mode and uses a return-to-zero code to transmit signals. After the power-on reset, the chip receives the number from the DIN terminal. According to the data, after receiving 24 bits, the DOUT port starts to forward data and provides input data for the next chip. DOUT port before forwarding Keep pulling low. At this point, the chip will not receive new data, and the three PWM output ports of the chips OUTR, OUTG, and OUTB are received according to the 24 bit data, the corresponding signal with different duty cycle is issued, and the signal period is 4 ms. If the input signal to the DIN terminal is the RESET signal, The chip sends the received data to the display, and the chip will re-receive the new data after the signal is finished. After receiving the first 24 bits of data, The data is forwarded through the DOUT port. The original output of the OUTR, OUTG, and OUTB pins remains unchanged before the chip receives the RESET code. Change, when receiving a low level RESET code above 80 μs, the chip will output the 24-bit PWM data pulse width just received to OUTR, On the OUTG, OUTB pins.

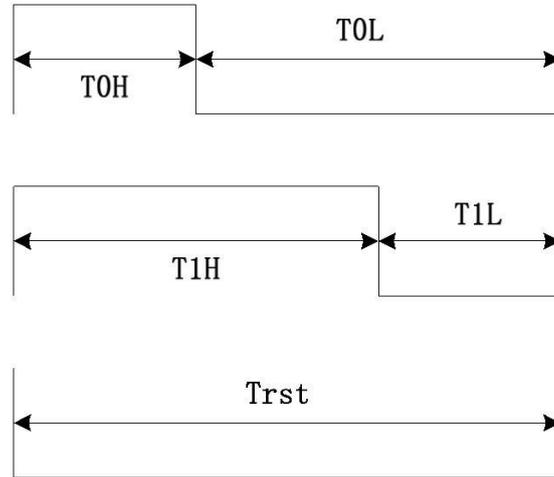
The chip adopts automatic shaping and forwarding technology, so that the number of cascaded chips is not limited by signal transmission, and only the speed of the screen is limited. For example, we design a 1024 cascade, which has a screen time of  $1024 \times 0.4 \times 2 = 0.8192\text{ms}$  (the data latency of the chip is 0.4 μs), there will be no flickering.

**11. The data transmission time (TH+TL=1.25μs ± 600ns)**

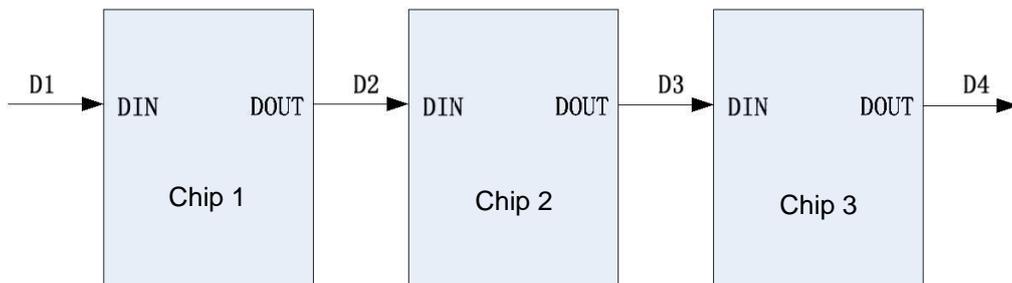
|      |                            |       |         |
|------|----------------------------|-------|---------|
| T0H  | 0 code, high level time    | 0.3μs | ±0.05μs |
| T0L  | 0 code, low level time     | 0.9μs | ±0.05μs |
| T1H  | 1 code, high level time    | 0.9μs | ±0.05μs |
| T1L  | 1 code, low level time     | 0.3μs | ±0.05μs |
| Trst | Reset code, low level time | 80μs  | ±0.05μs |

11. Timing waveform:

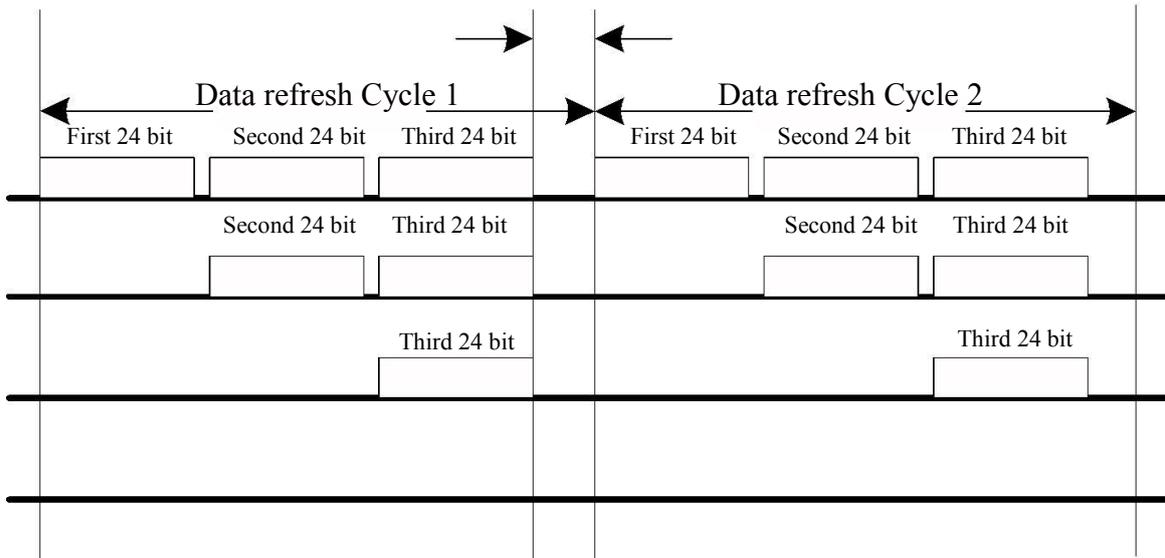
1) Input Code



2) Connect Mode



**12. The method of data transmission:**



**Note:** the D1 sends data for MCU, D2, D3, D4 for data forwarding automatic shaping cascade circui

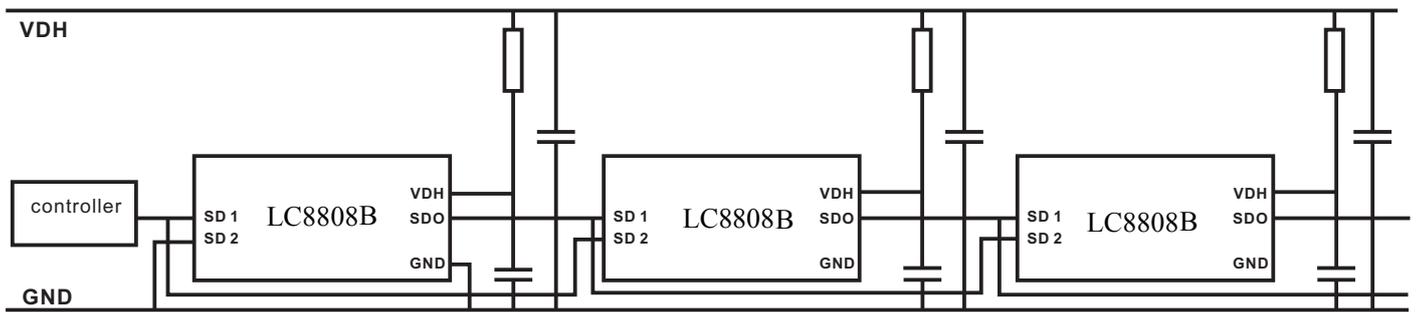
**14. The 24bit data Structure**

|    |    |    |    |    |    |    |    |    |    |    |    |
|----|----|----|----|----|----|----|----|----|----|----|----|
| B7 | B6 | B5 | B4 | B3 | B2 | B1 | B0 | G7 | G6 | G5 | G4 |
| G3 | G2 | G1 | G0 | R7 | R6 | R5 | R4 | R3 | R2 | R1 | R0 |

Note: high starting, in order to send data (B7 - B6 - ..... ..R0)

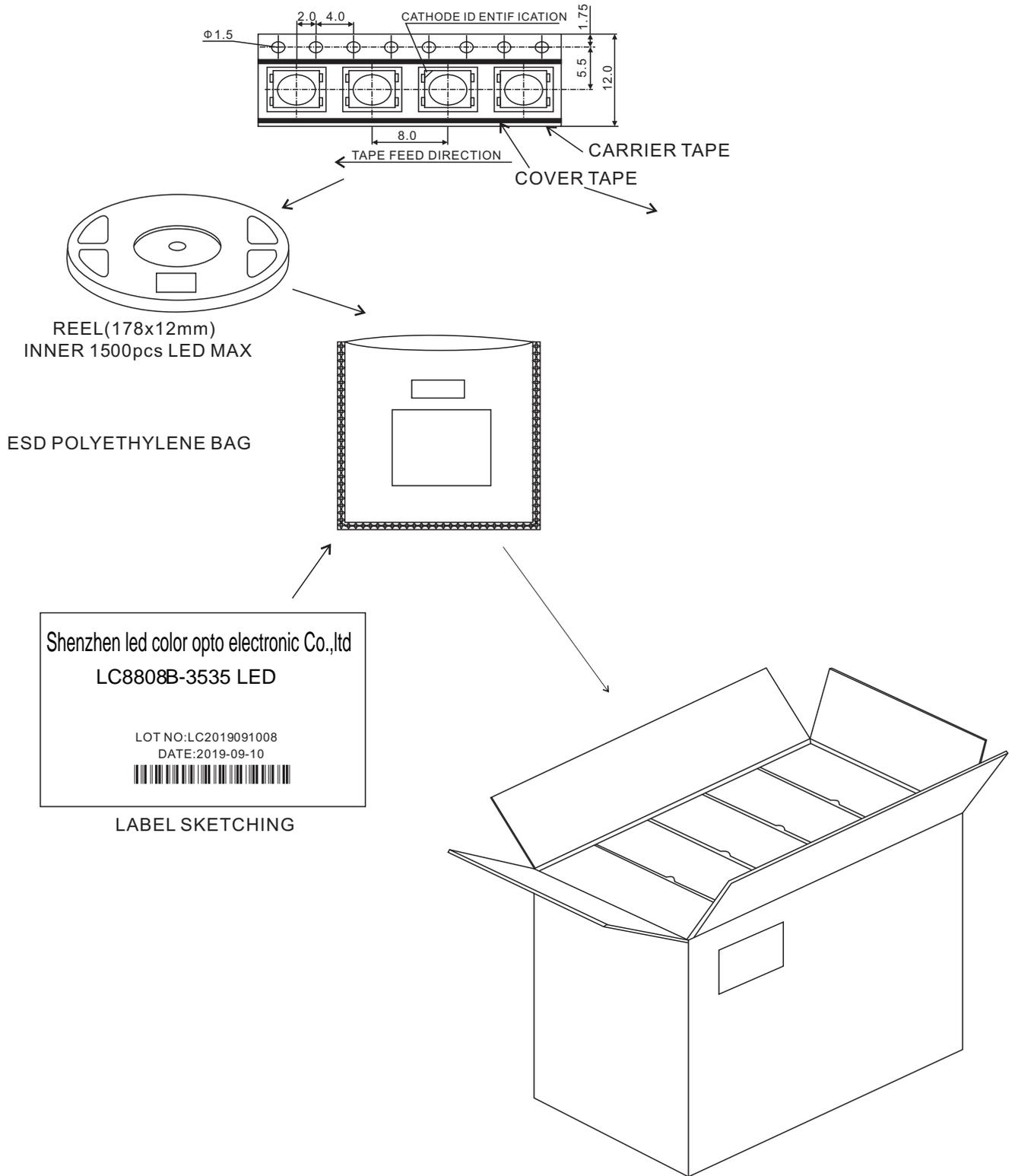
13. The typical application circuit:

LC8808B-3535 LED





**14. Packaging Standard:**



The reel pack is applied in SMD LED. The LEDs are packed in cardboard boxes after packaging in normal or anti-electrostatic bags. cardboard boxes will be used to protect the LEDs from mechanical shocks during transportation. The boxes are not water resistant and therefore must be kept away from water and moisture.

## 15. Attention

### 15.1 Dust & Cleaning

The LED use epoxy glue to package the 3535 Surface, epoxy surface can protect optical properties and improved anti-aging properties. However, epoxy is a softer material and prone to attract dust. While a minimal amount of dust and debris on the LED will not cause significant reduction in illumination. We still need to avoid dust falling on the LED surface. After open the bags it must be used immediately.

When you use trichloroethylene or acetone to clean, sometimes the LED surface will dissolve.

Avoid using organic solvent, it is recommended that isopropyl be used as a solvent for cleaning the LEDs. When using other solvents, it should be confirmed beforehand whether the solvents will dissolve the package and the resin or not.

Do not clean the LEDs by the ultrasonic. When it is absolutely necessary, the influence as ultrasonic cleaning on the LEDs depends on factors such as ultrasonic power. Baking time and assembled condition.

Before cleaning, a pre-test should be done to confirm whether any damage to the LEDs will occur.

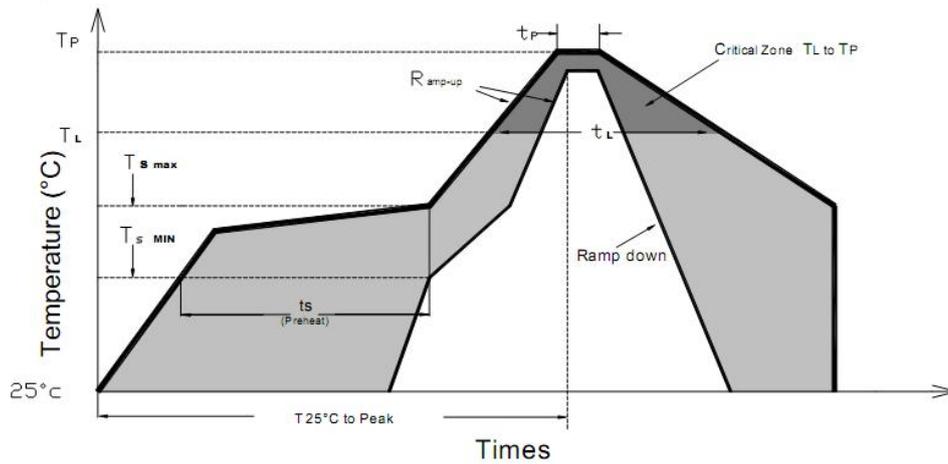
### 15.2 Dehumidification

LED COLOR smart led are moisture sensitive components, In IPC/JEDEC J-STD-020 MSL Level is 6. **No Matter the Package bag is open or not ,The LED must do dehumidification in the oven for 24 hours at 70 degree before use and used within 4 hours, otherwise it need to be dehumidified again**

### 15.3 Reflow Soldering Characteristics

In our Test, LED Color confirm those smart led are compatible with JEDEC J-STD-020C, Customers are required to follow the soldering temperature profile recommended by the solder paste manufacturer used.

Please note that this general guideline may not apply to all PCB design and reflow soldering equipment configurations.



| Profile Feature                                 | Lead-Based Solder | Lead-Free Solder |
|---|-------------------|------------------|
| Average Ramp-Up Rate (Ts max to Tp)             | 3 °C/second max.  |                  |
| Preheat: Temperature Min (Ts min)               | 100°C             | 150°C            |
| Preheat: Temperature Min (Ts max)               | 150°C             | 200°C            |
| Preheat: Time (ts min to ts max)                | 60-120 seconds    | 60-180 seconds   |
| Time Maintained Above: Temperature (TL)         | 183 °C            | 217 °C           |
| Time Maintained Above: Time (tL)                | 60-150 seconds    | 60-150 seconds   |
| Peak/Classification Temperature (TP)            | 215 °C            | 238 °C           |
| Time Within 5°C of Actual Peak Temperature (tp) | <10 seconds       | <10 seconds      |
| Ramp-Down Rate                                  | 6 °C/second max   | 6 °C/second max  |
| Time 25 °C to Peak Temperature                  | <6 minutes max    | <6 minutes max   |

Note: All temperatures refer to topside of the package, measured on the package body surface.

#### 15.4. Anti-static and surge protection for IC devices

Static electricity and surges can damage the LED products of IC devices, so appropriate protective measures must be taken;

The signal input and output ports of IC devices must be connected in series with protective resistors to prevent product failure due to surge or electrostatic shock ports;

In order to protect the LED products of IC devices, whenever you encounter LEDs, wear anti-static straps, anti-static straps and anti-static gloves.

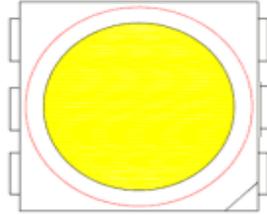
All devices and equipment must be grounded

It is recommended that each product be tested before shipment for relevant electrical tests to select defective products due to static electricity.

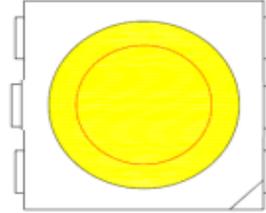
In the design of the circuit, consideration should be given to eliminating the surge to the LED

### 15.5 Other requirements

SMT nozzle requirements: (red circle refers to the inside diameter of the nozzle)



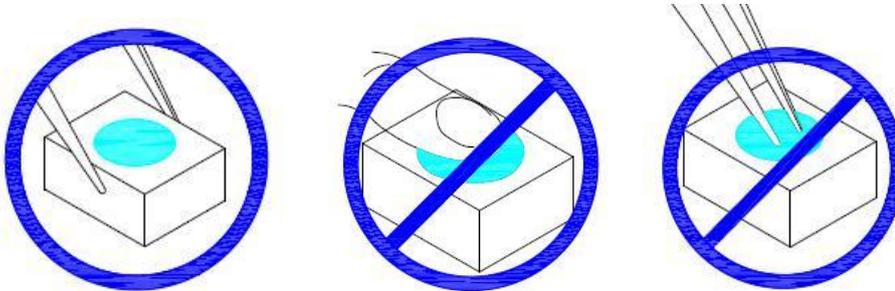
OK (the inside diameter of the nozzle is larger than the light-emitting area of the lamp)



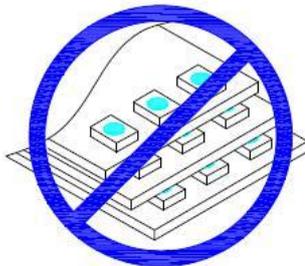
NG (the inside diameter of the nozzle is smaller than the lighting area of the lamp)

Pressing the colloid surface will affect the reliability of LED because the LED is advanced silicone-gel. And therefore precautions should be taken to avoid the strong pressure on the component. It's proper to make the LED be used in safe condition when using a suction nozzle. Silicon packing with soft and elastic, it greatly reduces thermal stresses and unable to bear external mechanical forces. Therefore, preventive measures should be taken in process of manually handling.

① Clip the LED from its side. Neither directly touch the gel surface with the hand or sharp instrument, it may damage its internal circuit.



② Not to be double stacked, it may damage its internal circuit.



- ③ Can not be stored in or applied in the acidic sites of PH<7.



**Modify Records**

| <b>Item NO.</b>     | <b>Rev. No.</b> | <b>Modify Content Summary</b> |                 |                   |
|---------------------|-----------------|-------------------------------|-----------------|-------------------|
| <b>LC8808B-3535</b> | <b>01</b>       | <b>Initial Document</b>       | <b>Andy Zhu</b> | <b>2019-09-09</b> |
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